

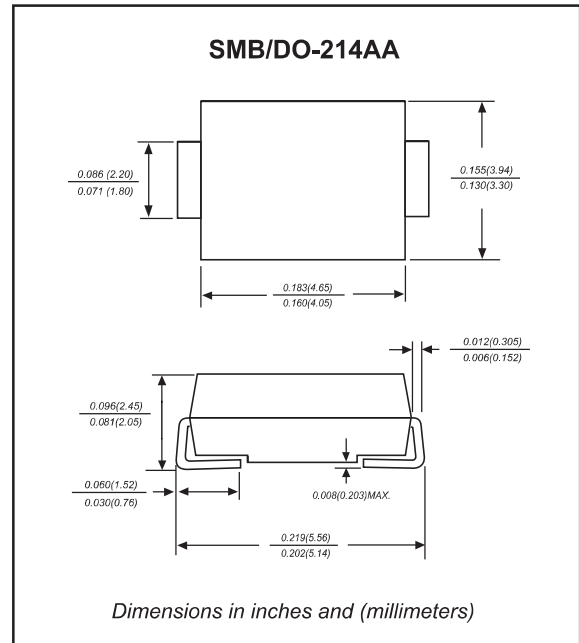
Features

- ▶ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ▶ For surface mounted applications
- ▶ Metal silicon junction, majority carrier conduction
- ▶ Low power loss, high efficiency
- ▶ Built-in strain relief, ideal for automated placement
- ▶ High forward surge current capability
- ▶ High temperature soldering guaranteed: 250°C/10 seconds at terminals
- ▶ Compliant to RoHS Directive 2011/65/EU
- ▶ Compliant to Halogen-free

Mechanical data

- ▶ **Case:** JEDEC DO-214AA molded plastic body
- ▶ **Terminals:** Solder plated, solderable per MIL-STD-750, Method 2026
- ▶ **Polarity:** Color band denotes cathode end
- ▶ **Mounting Position:** Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS		Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1		I_O			5.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)		I_{FSM}			120	A
Reverse current	$T_A = 25^\circ\text{C}$	$V_R = 20\text{V} - 60\text{V}$	I_R			0.5	mA
		$V_R = 80\text{V} - 200\text{V}$				0.1	
Reverse current	$T_A = 100^\circ\text{C}$	$V_R = 20\text{V} - 60\text{V}$	I_R			10	mA
		$V_R = 80\text{V} - 200\text{V}$				5	
Thermal resistance (1)	Junction to Ambient		$R_{\theta JA}$		60		$^\circ\text{C/W}$
	Junction to Case		$R_{\theta JC}$		23		
	Junction to Lead		$R_{\theta JL}$		25		
Diode junction capacitance	$f=1\text{MHz}$ and applied 4V DC reverse voltage		C_J		200		pF
Storage temperature			T_{STG}	-65		+150	$^\circ\text{C}$

Note: (1) Device mounted on p.c.b. with 10 mm x 20 mm x 0.1 mm copper pad area.

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	Operating temperature T _J , (°C)
SS52-B	20	14	20	0.55	-55 to +150
SS53-B	30	21	30		
SS54-B	40	28	40		
SS55-B	50	35	50	0.70	
SS56-B	60	42	60		
SS58-B	80	56	80	0.85	
SS510-B	100	70	100		
SS515-B	150	105	150	0.92	
SS520-B	200	140	200		

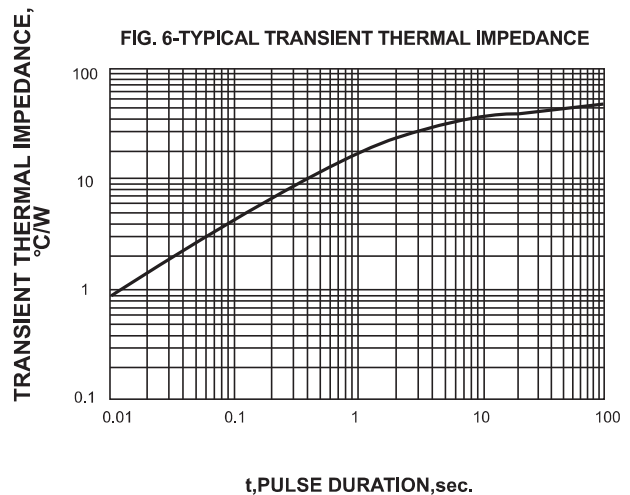
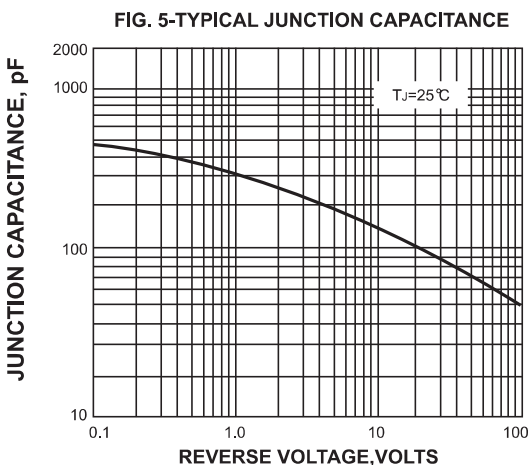
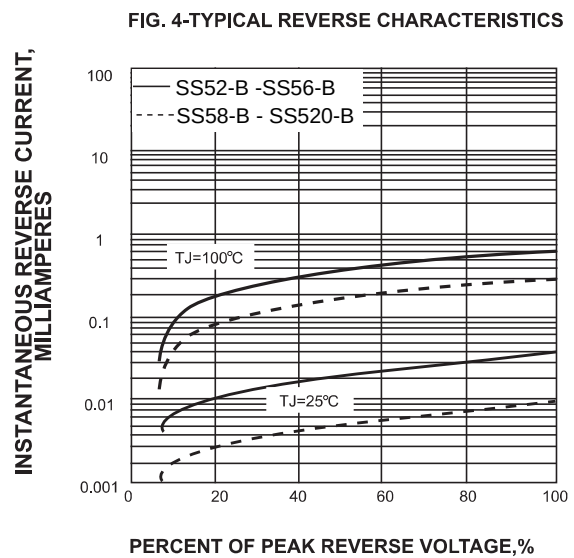
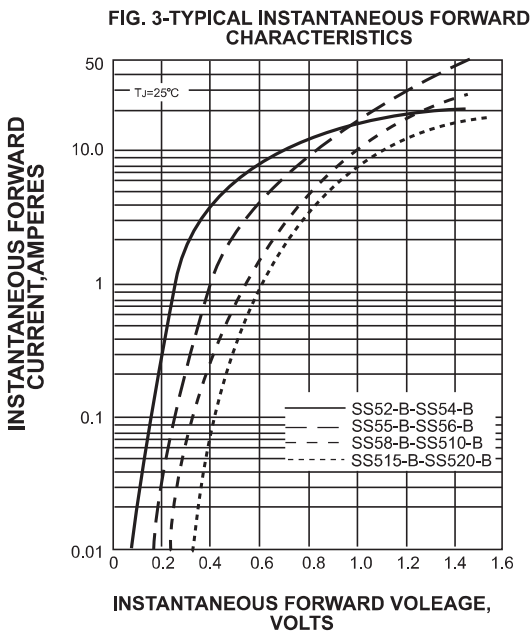
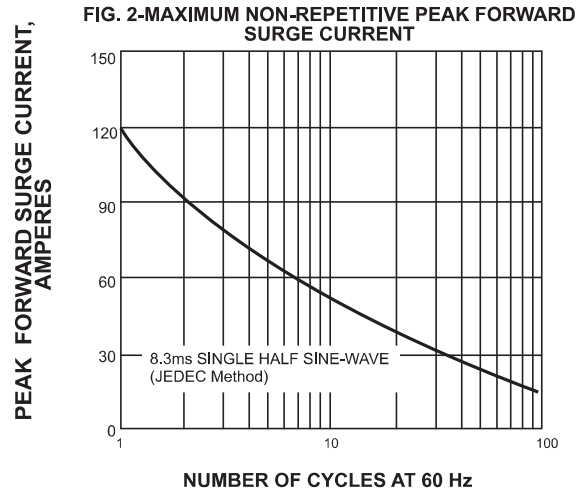
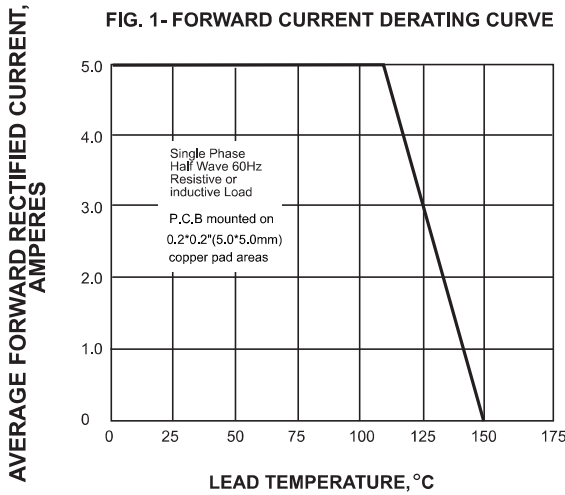
*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=5.0\text{A}$

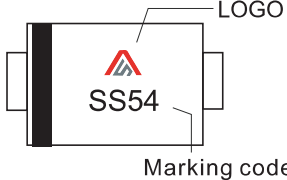
Rating and characteristic curves



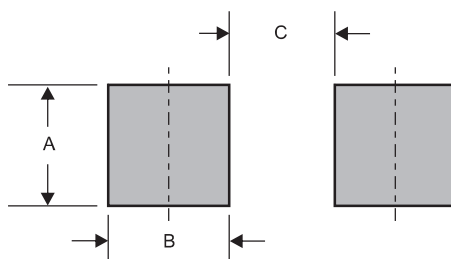
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code	Example
SS52-B	SS52	
SS53-B	SS53	
SS54-B	SS54	
SS55-B	SS55	
SS56-B	SS56	
SS58-B	SS58	
SS510-B	SS510	
SS515-B	SS515	
SS520-B	SS520	

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMB	0.090(2.30)	0.098(2.50)	0.070(1.80)